

Title (en)

Procedure for the continuous manufacture of microchip carrier cards and cards obtained via the seid procedure

Title (de)

Verfahren zum kontinuierlichen Herstellen von Microchipträgerkarten und sowie mit diesem Verfahren hergestellte Karten

Title (fr)

Procédé pour la fabrication en continu de cartes porteuses de microchip et cartes obtenues par ce procédé

Publication

EP 0858050 A3 20010328 (EN)

Application

EP 98101964 A 19980205

Priority

AR 9700508 A 19970207

Abstract (en)

[origin: EP0858050A2] It comprises placing in parallel at least three laminar bodies of a non-conducting material joined together one above the other, defining a single continuous composite band; die-stamping at least the intermediate band with at least one perforation, without die-stamping the other sheets, determining a housing for a microchip; the continuous composite band is then submitted to cutting into individual cards, which posses at least one cavity or housing. <IMAGE>

IPC 1-7

G06K 19/077

IPC 8 full level

B32B 37/20 (2006.01); **G06K 19/077** (2006.01)

CPC (source: EP)

B32B 37/203 (2013.01); **G06K 19/077** (2013.01); **G06K 19/07718** (2013.01); **B32B 2305/342** (2013.01); **B32B 2425/00** (2013.01)

Citation (search report)

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